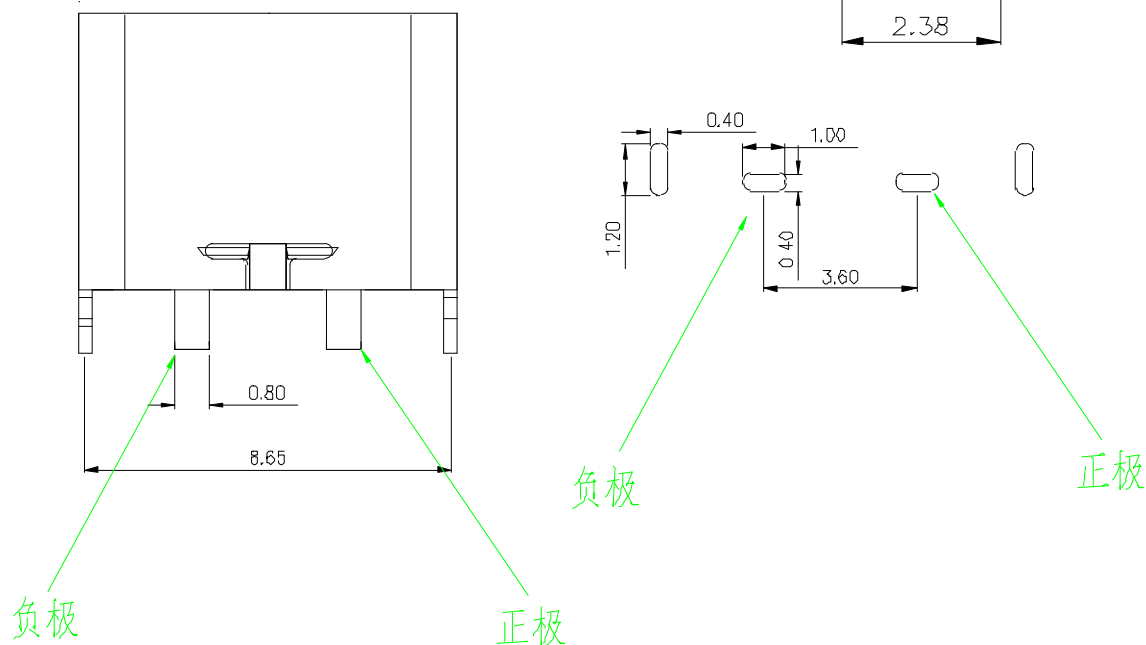


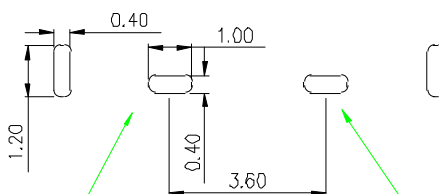
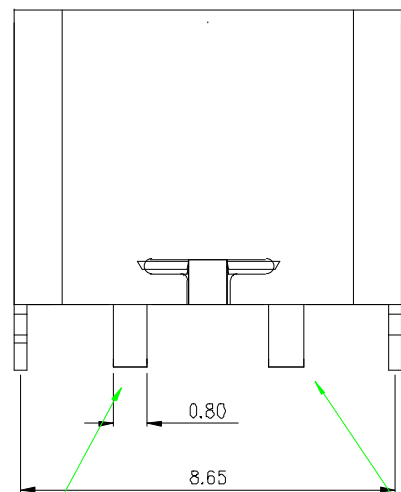
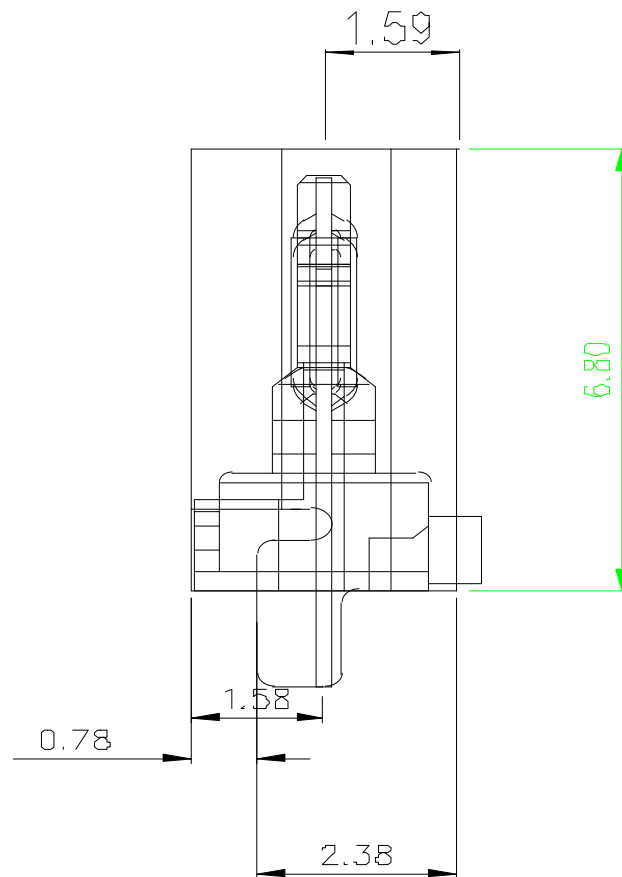
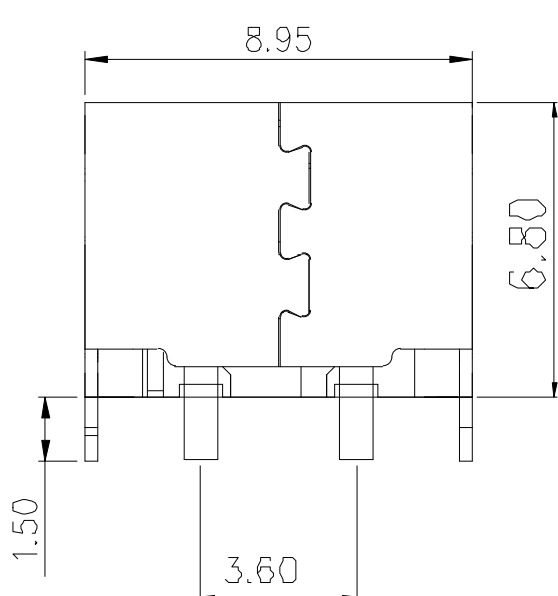
NOTE:

- 1.MATERIAL SPECIFICATION:
 - 1.HOUSING:HIGH TEMPERATURE RESISTANT PLASTIC,UL94 V-0.
 - 2.CONTACTS:COPPER ALLOY
 - 3.MID PLATE: STAINLESS STEEL
 - 4.FRONT SHELL: STAINLESS STEEL
- 2.PLATING SPECIFICATION:
 - 2-1.CONTACTS:
 - Ni 50u" MIN. UNDER PLATED OVER ALL.
 - Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
 - (GOLD PLATING THICKNESS FOLLOW THE P/N)
 - PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N
 - 2-2.FRONT SHELL:
 - SEE TABLE 1.
 - 2-3.SHIELD PLATE&EMI PLATE:
 - CLEAR ONLY
- 3.MECHANICAL PERFORMANCE,
 - 3-1.INSERTION FORCE: 0.5~2.0kgf.
 - 3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.
 - 3-3.DURABILITY: 5000 CYCLES.
- 4.ELECTRICAL PERFORMANCE,
 - 4-1. CURRENT RATING: 3.0A
 - VOLTAGE RATING: 5.0V
 - 4-2. LLCR:
 - VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.
 - SHIELD: 50mΩ/MAX.
 - LLCR MAX. CHANGE OF ALL PINS: 10mΩ.
 - 4-3.INSULATION RESISTANCE: 100MΩ MIN
 - 4-4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.
5. ENVIRONMENTAL PERFORMANCE:
 - OPERATING TEMPERATURE: -25°C~+85°C.
- 6.IR REFLOW:
 - THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260°C.



东莞市溪榜电子有限公司
DONG GUAN XIBANG ELECTRONICS CO., LTD.

TOLERANCE: X.X ±0.30 X.XX ±0.20 X.XXX ±0.10 X.XX ±0.10 X.X ±0.05 X.X ±0.05	DRAWN BY :	DATE :	PART NAME:	
			2015.08.18	TYPE-C2PIN立插板H6.5
	CHECKED BY :	DATE :	PART NO.	SEE TABLE
		2015.08.18	MOLD NO.	
	APPROVED BY :	DATE :	DRAW NO.	
		2015.08.18	SHEET NO.	1 OF 1
UNIT: mm [inch]				
SCALE:1:1 SIZE: A4				

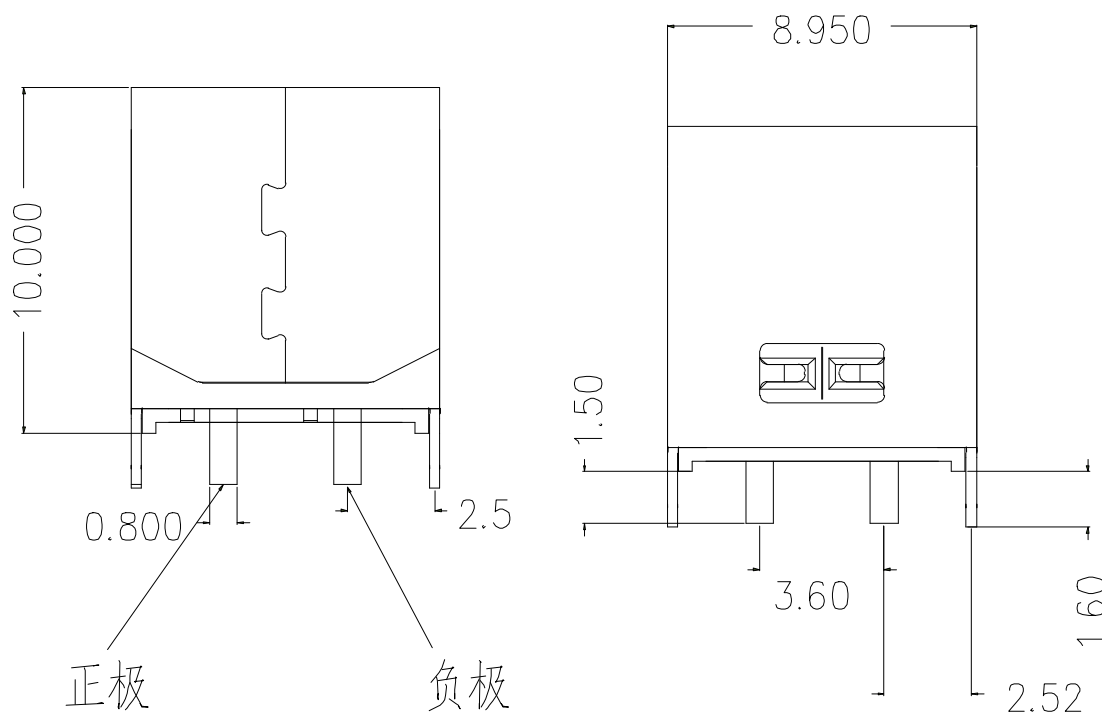
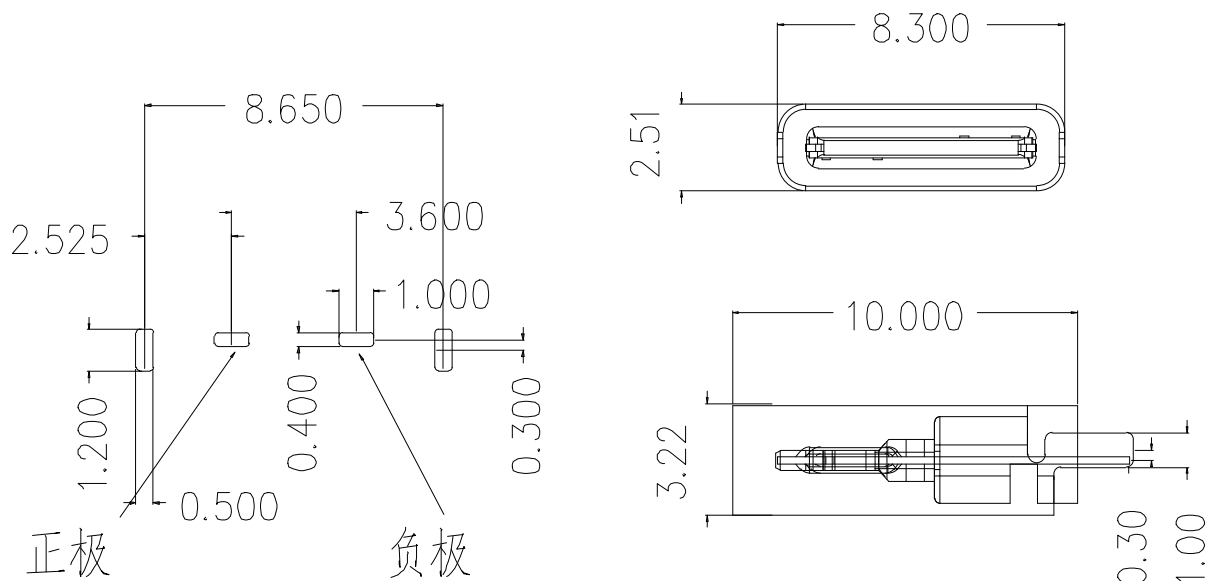


负极 正极 负极 正极

NOTE:

- 1.MATERIAL SPECIFICATION:
 - 1.HOUSING: HIGH TEMPERATURE RESISTANT PLASTIC,UL94 V-0.
 - 2.CONTACTS: COPPER ALLOY
 - 3.MID PLATE: STAINLESS STEEL
 - 4.FRONT SHELL: STAINLESS STEEL
- 2.PLATING SPECIFICATION:
 - 2-1.CONTACTS:
 - Ni 50u" MIN. UNDER PLATED OVER ALL.
 - Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
 - (GOLD PLATING THICKNESS FOLLOW THE P/N)
 - PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N
 - 2-2.FRONT SHELL:
 - SEE TABLE 1.
 - 2-3.SHIELD PLATE&EMI PLATE:
 - CLEAR ONLY
- 3.MECHANICAL PERFORMANCE,
 - 3-1.INSERTION FORCE: 0.5~2.0kgf.
 - 3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.
 - 3-3.DURABILITY: 5000 CYCLES.
- 4.ELECTRICAL PERFORMANCE,
 - 4-1. CURRENT RATING: 3.0A
VOLTAGE RATING: 5.0V
 - 4-2. LLCR:
 - VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.
 - SHIELD: 50mΩ/MAX.
 - LLCR MAX. CHANGE OF ALL PINS: 10mΩ.
 - 4-3.INSULATION RESISTANCE: 100MΩ MIN
 - 4-4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.
5. ENVIRONMENTAL PERFORMANCE:
 - OPERATING TEMPERATURE: -25°C~+85°C.
- 6.IR REFLOW:
 - THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260°C.

东莞市溪榜电子有限公司 DONG GUAN XIBANG ELECTRONICS CO., LTD.			
TOLERANCE: X.X ±0.30 X.XX ±0.20 X.XXX ±0.10 X.XX ±0.10 X.X ±0.05 X.X ±0.05 X.X ±0.05	DRAWN BY :	DATE :	PART NAME:
	CHECKED BY :	DATE :	TYPE-C2PIN立插板H6.8
	APPROVED BY :	DATE :	PART NO. SEE TABLE
UNIT: mm [inch] SCALE: 1:1 SIZE: A4		2015.08.18	MOLD NO.
		2015.08.18	DRAW NO.
		2015.08.18	SHEET NO. 1 OF 1



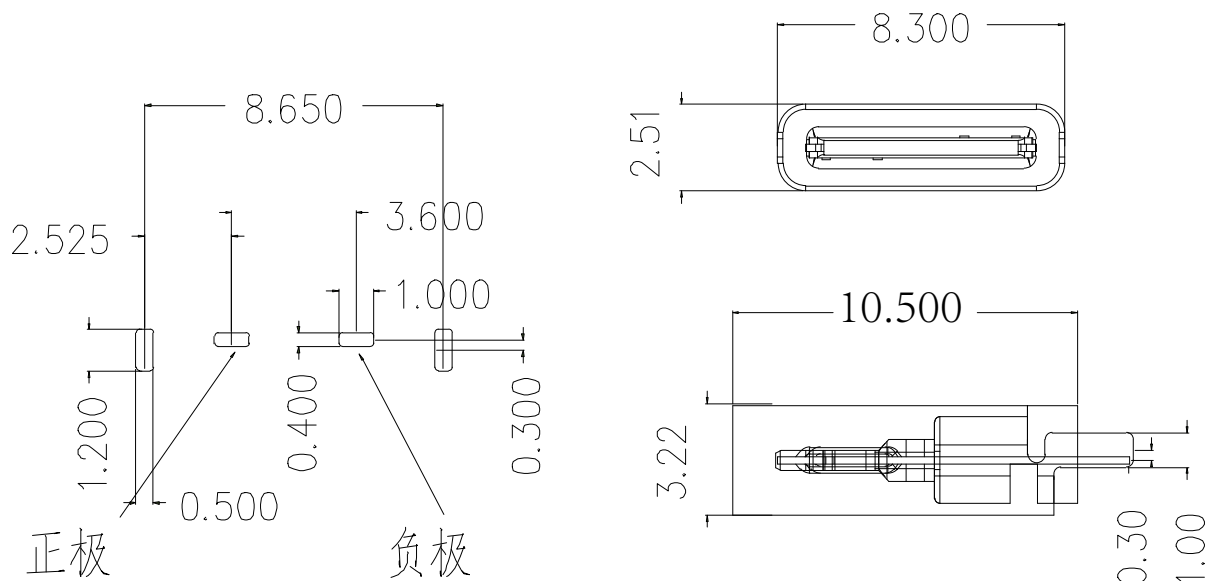
NOTE:

- 1.MATERIAL SPECIFICATION:
 - 1.HOUSING: HIGH TEMPERATURE RESISTANT PLASTIC,UL94 V-0.
 - 2.CONTACTS: COPPER ALLOY
 - 3.MID PLATE: STAINLESS STEEL
 - 4.FRONT SHELL: STAINLESS STEEL
- 2.PLATING SPECIFICATION:
 - 2-1.CONTACTS:
 - Ni 50u" MIN. UNDER PLATED OVER ALL.
 - Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
 - (GOLD PLATING THICKNESS FOLLOW THE P/N)
 - PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N
 - 2-2.FRONT SHELL:
 - SEE TABLE 1.
 - 2-3.SHIELD PLATE&EMI PLATE:
 - CLEAR ONLY
- 3.MECHANICAL PERFORMANCE,
 - 3-1.INSERTION FORCE: 0.5~2.0kgf.
 - 3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.
 - 3-3.DURABILITY: 5000 CYCLES.
- 4.ELECTRICAL PERFORMANCE,
 - 4-1. CURRENT RATING: 3.0A
 - VOLTAGE RATING: 5.0V
 - 4-2. LLCR:
 - VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.
 - SHIELD: 50mΩ/MAX.
 - LLCR MAX. CHANGE OF ALL PINS: 10mΩ.
 - 4-3.INSULATION RESISTANCE: 100MΩ MIN
 - 4-4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.
5. ENVIRONMENTAL PERFORMANCE:
 - OPERATING TEMPERATURE: -25°C~+85°C.
- 6.IR REFLOW:
 - THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260°C.

东莞市溪榜电子有限公司
DONG GUAN XIBANG ELECTRONICS CO., LTD.

TOLERANCE: X.X ±0.30 X.XX ±0.20 X.XXX ±0.10 X.XX° ±10° X.X° ±5°	DRAWN BY :	DATE :	PART NAME:	
			2015.08.18	TYPE-C2PIN立插板H10.0
	CHECKED BY :	DATE :	PART NO.	SEE TABLE
		2015.08.18	MOLD NO.	
	APPROVED BY :	DATE :	DRAW NO.	
		2015.08.18	SHEET NO.	1 OF 1

UNIT: mm [inch]
SCALE: 1:1 SIZE: A4



NOTE:

1.MATERIAL SPECIFICATION:

- 1.HOUSING: HIGH TEMPERATURE RESISTANT PLASTIC,UL94 V-0.
- 2.CONTACTS: COPPER ALLOY
- 3.MID PLATE: STAINLESS STEEL
- 4.FRONT SHELL: STAINLESS STEEL

2.PLATING SPECIFICATION:

2-1.CONTACTS:

- Ni 50u" MIN. UNDER PLATED OVER ALL.
- Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
- (GOLD PLATING THICKNESS FOLLOW THE P/N)
- PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N

2-2.FRONT SHELL:

SEE TABLE 1.

2-3.SHIELD PLATE&EMI PLATE:

CLEAR ONLY

3.MECHANICAL PERFORMANCE,

- 3-1.INSERTION FORCE: 0.5~2.0kgf.
- 3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.
- 3-3.DURABILITY: 5000 CYCLES.

4.ELECTRICAL PERFORMANCE,

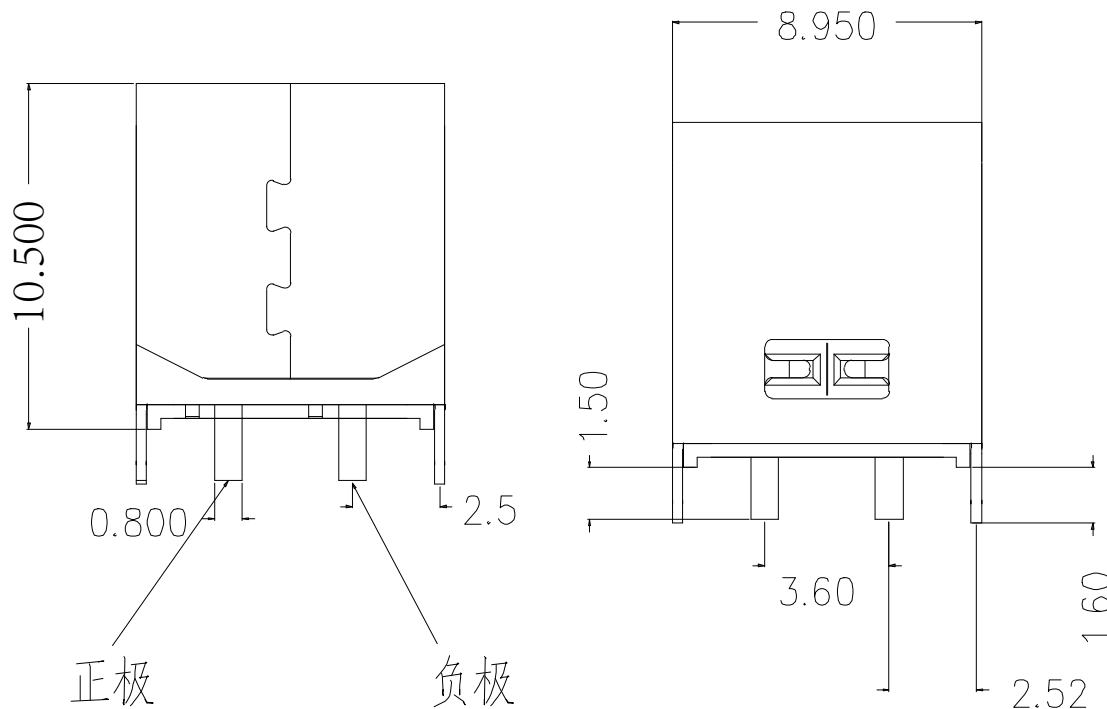
- 4-1. CURRENT RATING: 3.0A
VOLTAGE RATING: 5.0V
- 4-2. LLCR:
VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.
SHIELD: 50mΩ/MAX.
LLCR MAX. CHANGE OF ALL PINS: 10mΩ.
- 4-3.INSULATION RESISTANCE: 100MΩ MIN
- 4-4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.

5. ENVIRONMENTAL PERFORMANCE:

OPERATING TEMPERATURE: -25°C~+85°C.

6.IR REFLOW:

THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260°C.



东莞市溪榜电子有限公司 DONG GUAN XIBANG ELECTRONICS CO.,			
TOLERANCE: L.T.D. X.XX ±0.30 X.XXX ±0.20 X.XXX ±0.10 X.X ±10° X.X ±5°	DRAWN BY : 李毅	DATE : 2015.08.18	PART NAME: TYPE-C2PIN立插板H10.5
	CHECKED BY:	DATE : 2015.08.18	PART NO. SEE TABLE
	APPROVED BY:	DATE : 2015.08.18	MOLD NO.
UNIT: mm [inch]			DRAW NO.
SCALE:1:1 SIZE: A4			SHEET NO. 1 OF 1